IHS iSuppli Teardown Analysis



has acquired



2012

The teardown analysis service from IHS iSuppli provides complete, detailed analyses of electronics from small devices such as wireless handsets and netbooks to larger equipment such as servers and base stations. IHS iSuppli delivers a complete assessment of all electronic, electromechanical, and mechanical components. This IHS iSuppli service is the ultimate competitive benchmarking tool -- providing the highest quality, most detailed view available of the design from both a cost and structural assessment perspective.

The teardown analysis is presented online to provide users maximum flexibility in reviewing and using the teardown information. This system, unlike a standard document, intuitively allows users to quickly drill down to the information they need, by sub-assembly. Summary level information is also always available at every level of system or sub-assembly. Whether you are interested in top-level numbers, or specific components and costs, it's all there.

Teardown information is both downloadable (in the form of Excel, JPG, and PDF files), and navigable in an interactive online format – point and click on sub-assemblies, photos and interactive cost tables to see details and summaries. License as many users as you wish at no additional cost.

Teardown Analysis Download Files

PDF ABSTRACT - Teardown Analysis 2011 [1.9MB] ZIP High Resolution Photographs - PCB's - Apple iPhone 4S (16GB) [12.4MB] PDF Apple iPhone 4S (16GB) [4.0MB] UNK Bill of Materials - Apple iPhone 4S (16GB) [954KB]

Executive Summary

Overview / Main Features

The iPhone 4S disappointed a lot of fans at first. Many of them were disappointed that despite being a new phone, the iPhone was called the iPhone 4S, and not iPhone 5, suggesting that the public starts to get caught up in their own fantasies about Apple products, and that the public have ever-accelerating expectations of Apple. The iPhone 4S is, as it implies, a souped-up iPhone 4 version, just as the 3GS was a souped-up version of the iPhone 3G. It stood to reason that Apple would remain conservative, and try and get as many cost reductions they could by leveraging similar, or in some cases, the same components used in the iPhone 4.

Furthermore, with the introduction of the 4S, Apple now has a portfolio of 3 iPhone 4Ss, two downgraded iPhone 4s (8GB configuration only), and a downgraded iPhone 3GS. Apple now has subsidized phones through carriers at the \$200 level, the \$100 level and the \$0 level. This approach has been a hallmark of other Apple designs, like the Prod line. Offer though caveral price points, establish the brand with new consumers and young consumers, then those users will ultimately walk up the pricing staticase, bring increasing future revenues.

But with each new iPhone revision – increasing attention and steeply ramping sales volumes make each new release more interesting than the last. HS (Suppli currently forecasts total unit sales of 85 million units for all iPhone models mixed in 2011 alone The iPhone 45 is expected to represent 40 million units of that in 2011, doubling to 80 million or so in 2012.

Online Teardown Navigation

Main PCB
Display / Touchscreen

Other - Enclosures / Final Assembly
Camera Assembly
Box Contents
Rettory

Misc PCB Assemblies

BOM Analysis

	Click above for more d	letail			Cli	above for more detail	91.5	%					
Index	Component Type	Qty	Manufacturer	Manufacturer	Component Description	Markings		Per	Total	Insertion	Hand	Insertion Cost	Data Sheet Links
			Name	Part Number			를	Componer	nt Compone	Method	Insert	(Hand/Auto)	
							Ĕ	Cost	nt Cost	V 2000000000000000000000000000000000000	(sec)		
	.	2 E	1 6	1 6				SUSD	SUSD .				
12.0	Display	1			Display Module - 3.5" Diagonal, 16.7M Color TFT, 960 x 640 Pixel			\$23,0000	\$23,0000	Hand	20	\$0.0159	
7.0	Memory	1	Hymix	H20TDG8UD1MYR	Flash - NAND, 16GB, MLC	hynix, H2DTDG8UD1MYR, BC A		\$19.2000	\$19.2000	Auto		\$0.0003	http://www.hynix.com/no/pdfDownload.isp?path
14.0	Camera	1			Rear Camera Module - 8MP, BSI CMOS, 1/3.2" Format, Auto Focu	is DNL 136, 10989D, NT71D		\$16,4000	\$16,4000	Hand	20	\$0.0159	
1.0	Logic	1	Samsung Semiconductor	APL0498	Applications Processor - Dual Core, 45nm, PoP	S026KR2, 1131 (Die Marking: Af		\$14.9871	\$14.9871	Auto		\$0.0003	
250.0	Metals	1			Enclosure, Main Chassis - Machined Metal Frame, Stamped / For			\$14.3200	\$14,3200	Hand	20	\$0.0159	
13.0	Touchscreen	1			Touchscreen Assembly / Display Window - 3.5" Diagonal, Capac	R FA14, 110719 TYJ, 816-0420 05		\$14.0000	\$14,0000	Hand	20	\$0.0159	
2.0	Memory	1	Samsung Semiconductor	K3PE4E400B-XGC1	SDRAM - Mobile DDR2-667, 4Gb, 1.2V, PoP	Logo A5, APL0498 339S0130, K		\$9,2000	\$9.2000	Auto		\$0.0003	http://www.samsung.com/global/business/semico
3.0	Logic	1	Qualcomm	MDM6610	Baseband Processor - Dual-Mode, GSMEDGE/EVDOrB/HSPA, M			\$9.0677	\$9.0677	Auto		\$0.0003	
16.0	Rechargeable	1	Amperex Technology	423282	Battery - Li-Polymer, 3.7V, 1430mAh, 5.3Whr, w/ Integral Flex, &			\$6.1900	\$6,1900	Hand	15	\$0.0119	http://www.atbatlery.com/
30.0		1	Murata		BT / WLAN Module - Contains Broadcom BCM4330 & RF Switch,			\$5,9000	\$5,9000	Auto		\$0.0003	
195.0	PCB	1	Meiko Electronics		10-Layer - FR4/RCF HDI, Stacked Via, Lead-Free, Halogen-Free	MDK MB-60W 94V-0, 820-3031-		\$4,5300	\$4,5300	Hand	20	\$0.0159	http://www.melko-elec.com/english/index.html
4.0	Analog	1	Qualcomm	RTR8605	RF Transceiver - Dual Mode, GSMEDGE/EVDOrB/HSPA, Muti-Ba	in RTR8605, AAM849.0, E4127004		\$4,3004	\$4,3004	Auto		\$0.0003	
5.0	Analog		Ousloome	PM8028	Downer Management IC - for Ougloome Chinast	Ouslonme 0888028 A12170 1		\$2,2788	\$2.2788	Auda		\$0,0003	

For customer-driven projects, IHS iSuppli conducts a preliminary meeting with the client to assess goals; review standard project scope and deliverables; and establish costs and a timeline for delivery. IHS iSuppli can accommodate a wide variety of specific information requirements, which may be beyond the scope of our 'standard' offering, including such services as analysis of modules, elaborated silicon die analyses, etc. The service fee does not include the cost of the device being analyzed. Customers are responsible for providing the device for analysis.

Key Issues Addressed

- How competitive are our designs from a technical perspective?
- Where does our competition stand in terms of design sophistication?
- Are our costs in line with those of our competitors?
- How much does it cost to add certain product features?
- What new or evolving solutions could we use in future designs that will increase performance and save money?
- How can we better position and differentiate our products?
- What components are contained in our product?

Applicable To

- OEMs
 - Market Research Managers
 - Competitive Intelligence Managers
 - Strategic Product Marketing Managers
 - Strategic Design / Technical Managers
 - Strategic Purchasing Management
- · Component Manufacturers
 - Strategic Product Marketing
 - Market Research
- · Service Providers
 - Strategic Purchasing

Deliverables

The teardown analysis is presented online to provide users maximum flexibility in reviewing and using the teardown information.

There are two primary means of accessing this information:

- · Downloadable Files Including:
 - Detailed Bill of Materials (BOM) Analysis (Excel file) with interactive cost summary tables
 - High resolution PCB photo packet
 - PDF report version
- Online Interactive Presentation Quickly drill down to what you need without flipping through lengthy documents. This includes:
 - Photo analysis of disassembly
 - Executive Summary with key facts and figures
 - Online interactive cost tables

Executive Summary

- Key facts and figures on the device, cost assessment, major components used, etc.
- Key takeaways everything you need to know at a high level about the device and teardown

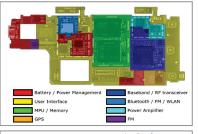
BOM Analysis

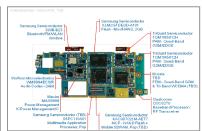
- Complete list of all electronic, electro-mechanical, and mechanical components. Most line items include pin count, package measurements, manufacturer names, part numbers, and all include component and insertion costs.
- Complimentary Summary Cost Analysis is included to enable views of cost summaries by Assembly, Function, Component Family, Component Type, Top Cost Drivers, and Major Integrated Circuits (ICs).
- Labor rates, country of origin, pricing methodology, device specific conversion costs are provided enabling transparency and understanding of the analysis presented.
- Complimentary Overall Cost Assumptions tab is included to enable
 the customer to include Pre Production Costs (NRE, IP, Software
 royalty/licensing fees), and Post Production Costs (manufacturing
 overhead, margin, transportation, logistics, sales/marketing costs)
 that a customer may want to see included in a per unit BOM cost.

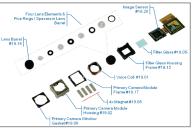
Photo Analysis

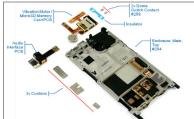
- Annotated and non annotated photos (thumbnail or full size view) of all device parts (sub-assemblies, printed circuit boards, and mechanical assemblies and parts).
- Annotated photos with index numbers that correlate to line items in the BOM.
- Major Component identification manufacturers' names, and part numbers.
- · Color coded Functional areas (provided when applicable).
- Block diagrams providing a functional analysis of the device analyzed (provided when applicable and agreed upon with customer at Project Kick Off).
- · Microscopic Dies shots and marking photos



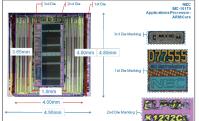




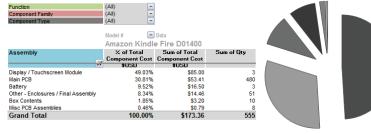














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